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Docket No. 259189US40PCT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Motoo ASAI, et al.

SERIAL NO: 10/509,899

GAU: 2633

FILED: June 29, 2005

EXAMINER:

FOR: SUBSTRATE FOR MOUNTING IC CHIP, MANUFACTURING METHOD OF SUBSTRATE FOR MOUNTING IC CHIP, DEVICE FOR OPTICAL COMMUNICATION, AND MANUFACTURING METHOD OF DEVICE FOR OPTICAL COMMUNICATION

## INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

## REFERENCES

- ☒ The applicant(s) wish to make of record the references cited in the attached Submission of Third Party Publications and listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available unedited computer generated English translations of pertinent portions of any non-English language references.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

## RELATED CASES

- ☐ Attached is a list of applicant's pending application(s), published application(s) or issued patent(s) which may be related to the present application. In accordance with the waiver of 37 CFR 1.98 dated September 21, 2004, copies of the cited pending applications are not provided. Cited published and/or issued patents, if any, are listed on the attached PTO form 1449.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

## CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

## DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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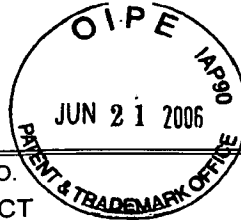
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ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /B.J./



Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 259189US40PCT		SERIAL NO. 10/509,899	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Motoo ASAI, et al.			
				FILING DATE June 29, 2005		GROUP <del>2633</del> 2814	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
<b>FOREIGN PATENT DOCUMENTS</b>							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION		
					YES	NO	
/B.J./	AO	5-211202	08/20/1993	Japan (with English Abstract and unedited computer generated English translation)	X		
/B.J./	AP	2001-33665	02/09/2001	Japan (with English Abstract and unedited computer generated English translation)	X		
/B.J./	AQ	2001-278941	10/10/2001	Japan (with English Abstract and unedited computer generated English translation)	X		
/B.J./	AR	2002-76376	03/15/2002	Japan (with English Abstract and unedited computer generated English translation)	X		
	AS						
	AT						
	AU						
	AV						
<b>OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)</b>							
	AW	Yuzo ISHII, et al., "Large-Tolerant "OptoBump" Interface for Interchip Optical Interconnections", IEICE Transactions C, vol. J84-C, no. 9, September 2001, pages 793-799, with partial English translation					
	AX						
	AY						
	AZ					<input type="checkbox"/> Additional References sheet(s) attached	
Examiner				/Bilkis Jahan/		Date Considered 06/12/2008	
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /B.J./